



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

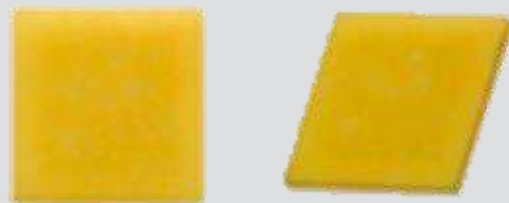
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## Middle Power LED Series Flip Chip Package

# LM102A



LM102A opens up a new world of lighting design with its high output and small form factors

### Features & Benefits

- Greater freedom of design with compact package size
- High degree of reliability with plastic-free structure
- Low thermal resistance
- High efficiency providing optimized solution
- Compact footprint (1.30 x 1.30 mm)

## Applications

### Indoor Lighting:

- Downlight
- LED Bulbs
- LED Tubes
- MR / PAR
- Ambient Light
- Ceiling Light

## Table of Contents

1.	Characteristics	-----	3
2.	Product Code Information	-----	6
3.	Typical Characteristics Graphs	-----	15
4.	Outline Drawing & Dimension	-----	17
5.	Reliability Test Items & Conditions	-----	19
6.	Soldering Conditions	-----	20
7.	Tape & Reel	-----	21
8.	Label Structure	-----	23
9.	Packing Structure	-----	24
10.	Precautions in Handling & Use	-----	26

## 1. Characteristics

### a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Operating Temperature	$T_a$	-40 ~ +85	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +120	°C	-
LED Junction Temperature	$T_j$	125	°C	-
Forward Current	$I_F$	250	mA	-
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	±2	kV	-

**b) Electro-optical Characteristics** ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage ( $V_F$ )	V	3F	-	-	5.89	-
Reverse Voltage (@ $-10 \mu\text{A}$ )	V			-10.0	-	-
Color Rendering Index ( $R_a$ )	-	8		80	-	-
Special CRI (R9)	-			0	-	-
Thermal Resistance (junction to chip point)	K/W			-	2	-
Beam Angle	$^\circ$			-	145	-

**Note:**

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1 \text{ V}$ , luminous flux =  $\pm 5 \%$ , CRI =  $\pm 3$ , R9 =  $\pm 6.5$

**c) Luminous Flux Characteristics ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**

Item	CRI	Nominal CCT (K)	SA		SB		SC		SD		SE		SF	
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
			79	87	87	95	95	103	103	111	111	119	119	127
Luminous Flux ( $\Phi_v$ )	70	3000												
		3500												
		4000												
		5000												
		5700												
		6500												
	80	2700												
		3000												
		3500												
		4000												
		5000												
		5700												
	90	6500												
		2700												
		3000												
			3500											

**Note:**

- 1) The LM102A is tested in pulsed condition at rated test current (10 ms pulse width)
- 2) Samsung maintains measurement tolerance of: luminous flux =  $\pm 5 \%$

## 2. Product Code Information (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 85 °C)

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	C	S	8	W	T	9	3	H	P	L	2	W	L	S	0	3	F

Digit	PKG Information	Code	Specification
1 2 3	Samsung Chip	<b>SCS</b>	
4	CRI	7 8 9	Min. 70 Min. 80 Min. 90
5	CCT (K)	W V U T R Q P	2700 3000 3500 4000 5000 5700 6500
6	Chip Shape	T	Square
7 8 9	Chip Size (μm)	<b>93H</b>	930x930x170μm
10 11 12	Product Purpose	<b>PL2</b>	PoC for Lighting
13	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
14	MacAdam Step	L U	Single Bin for MacAdam 5-step      L(MacAdam 5-step Bin) Single Bin for MacAdam 3-step      U(MacAdam 3-step Bin)
15 16	Luminous Flux (lm)	<b>S0</b>	Bin Code: SA, SB, SC, SD, SE, SF
17 18	Forward Voltage (V)	<b>3F</b>	5.6~6.2      Bin Code: <b>39</b> 5.6~5.9 5.6~6.2      Bin Code: <b>9F</b> 5.9~6.2



a) Luminous Flux Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ °C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
70	3000	SCS7VT93HPL2V☆S03F	SD	103 ~ 111
			SE	111 ~ 119
	3500	SCS7UT93HPL2U☆S03F	SD	103 ~ 111
			SE	111 ~ 119
	4000	SCS7TT93HPL2T☆S03F	SE	111 ~ 119
			SF	119 ~ 127
	5000	SCS7RT93HPL2R☆S03F	SE	111 ~ 119
			SF	119 ~ 127
	5700	SCS7QT93HPL2Q☆S03F	SE	111 ~ 119
			SF	119 ~ 127
	6500	SCS7PT93HPL2P☆S03F	SE	111 ~ 119
			SF	119 ~ 127

**Note:** “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ( $I_f = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
80	2700	SCS8WT93HPL2W☆S03F	SC	95 ~ 103
			SD	103 ~ 111
	3000	SCS8VT93HPL2V☆S03F	SC	95 ~ 103
			SD	103 ~ 111
	3500	SCS8UT93HPL2U☆S03F	SD	103 ~ 111
			SE	111 ~ 119
	4000	SCS8TT93HPL2T☆S03F	SD	103 ~ 111
			SE	111 ~ 119
	5000	SCS8RT93HPL2R☆S03F	SE	111 ~ 119
			SF	119 ~ 127
	5700	SCS8QT93HPL2Q☆S03F	SD	103 ~ 111
			SE	111 ~ 119
	6500	SCS8PT93HPL2P☆S03F	SD	103 ~ 111
			SE	111 ~ 119

**Note:** “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
90	2700	SCS9WT93HPL2W☆S03F	SA	79 ~ 87
			SB	87 ~ 95
	3000	SCS9VT93HPL2V☆S03F	SA	79 ~ 87
			SB	87 ~ 95
	3500	SCS9UT93HPL2U☆S03F	SA	79 ~ 87
			SB	87 ~ 95

**Note:** “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

b) Color Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ °C}$ )

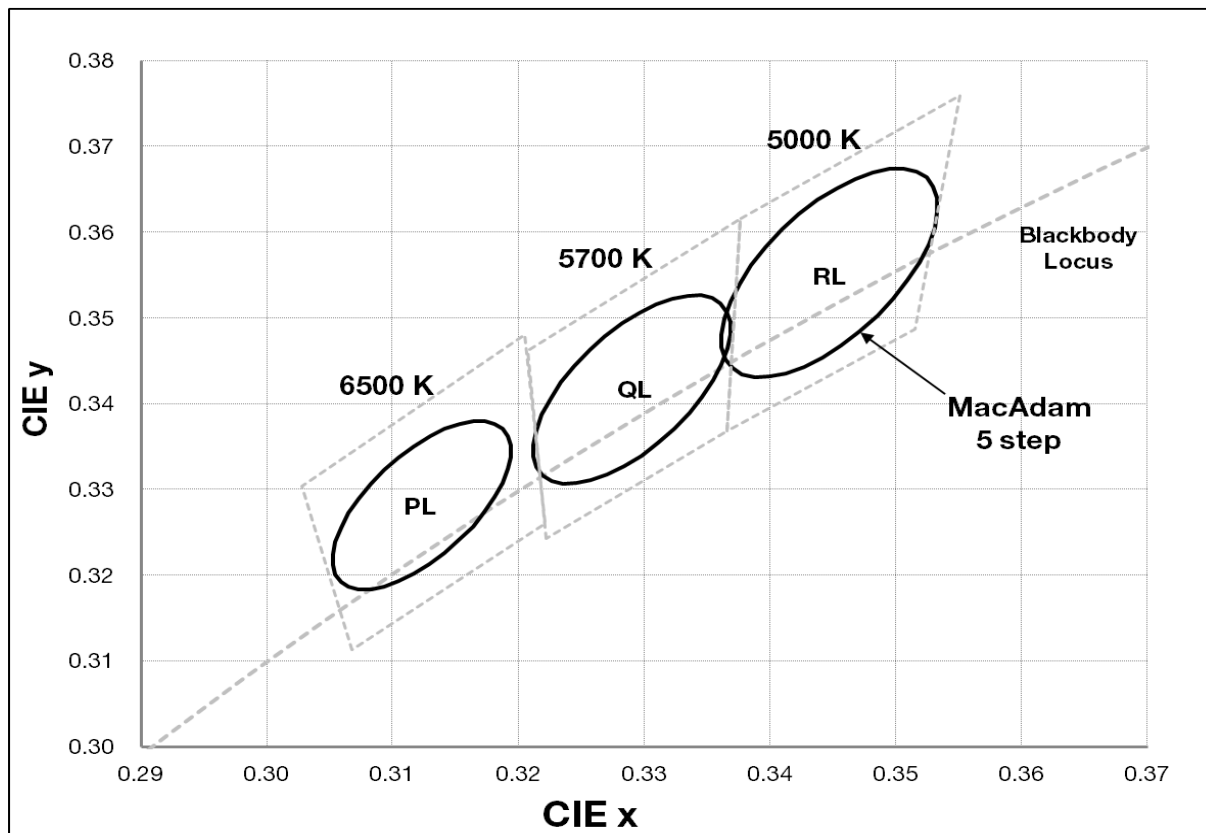
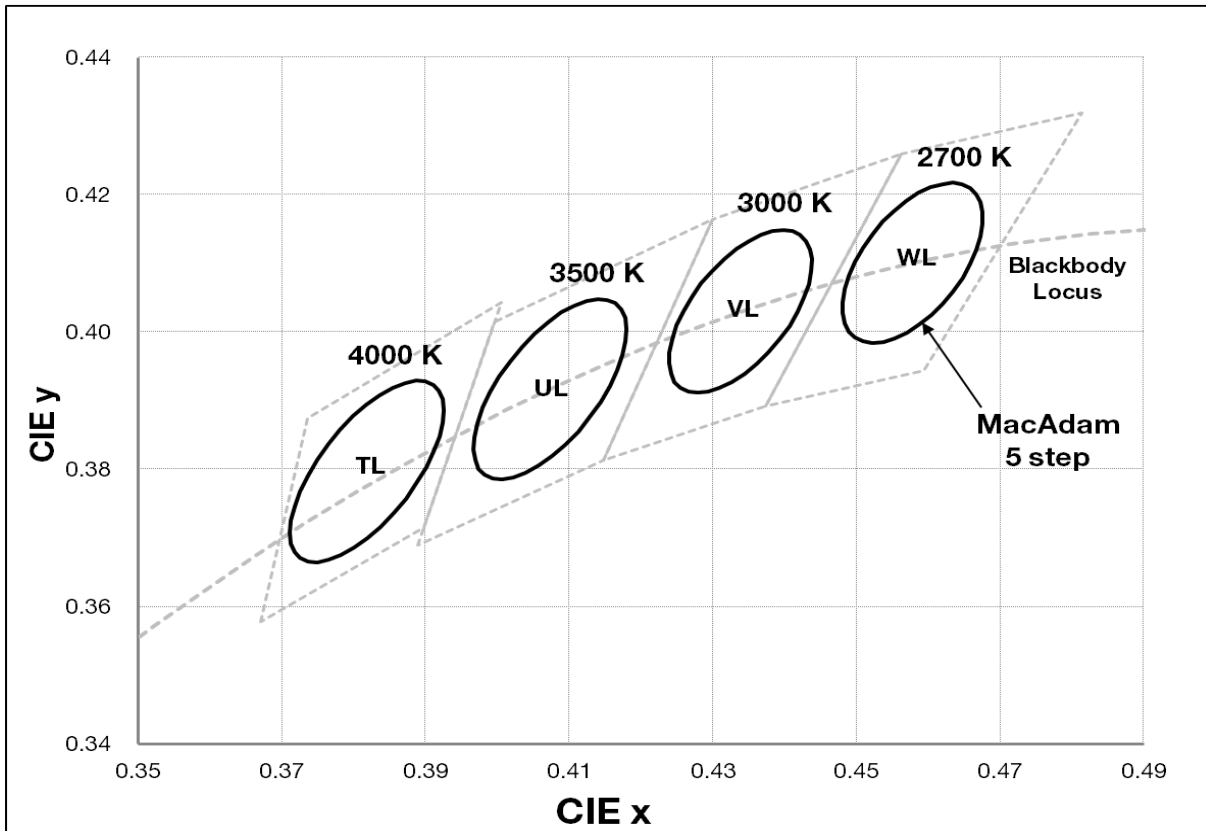
CRI Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins	
70	3000	SCS7VT93HPL2V☆S03F	VL	VL	
			VU	VU	
	3500	SCS7UT93HPL2U☆S03F	UL	UL	
			UU	UU	
	4000	SCS7TT93HPL2T☆S03F	TL	TL	
			TU	TU	
	5000	SCS7RT93HPL2R☆S03F	RL	RL	
			RU	RU	
	5700	SCS7QT93HPL2Q☆S03F	QL	QL	
			QU	QU	
	6500	SCS7PT93HPL2P☆S03F	PL	PL	
			PU	PU	
	80	2700	SCS8WT93HPL2W☆S03F	WL	WL
				WU	WU
3000		SCS8VT93HPL2V☆S03F	VL	VL	
			VU	VU	
3500		SCS8UT93HPL2U☆S03F	UL	UL	
			UU	UU	
4000		SCS8TT93HPL2T☆S03F	TL	TL	
			TU	TU	
5000		SCS8RT93HPL2R☆S03F	RL	RL	
			RU	RU	
5700		SCS8QT93HPL2Q☆S03F	QL	QL	
			QU	QU	
6500		SCS8PT93HPL2P☆S03F	PL	PL	
			PU	PU	
90	2700	SCS8WT93HPL2W☆S03F	WL	WL	
			WU	WU	
	3000	SCS8VT93HPL2V☆S03F	VL	VL	
			VU	VU	
	3500	SCS8UT93HPL2U☆S03F	UL	UL	
			UU	UU	

**Note:** “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

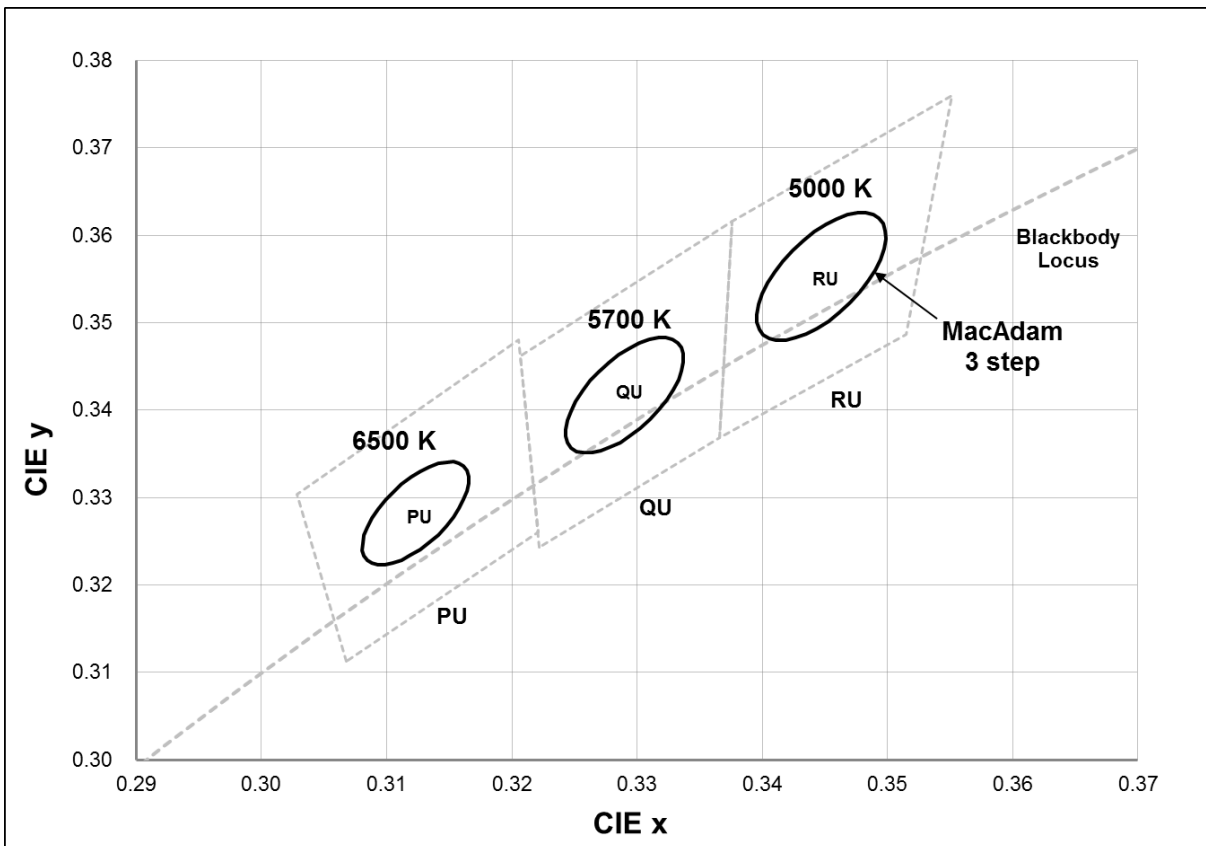
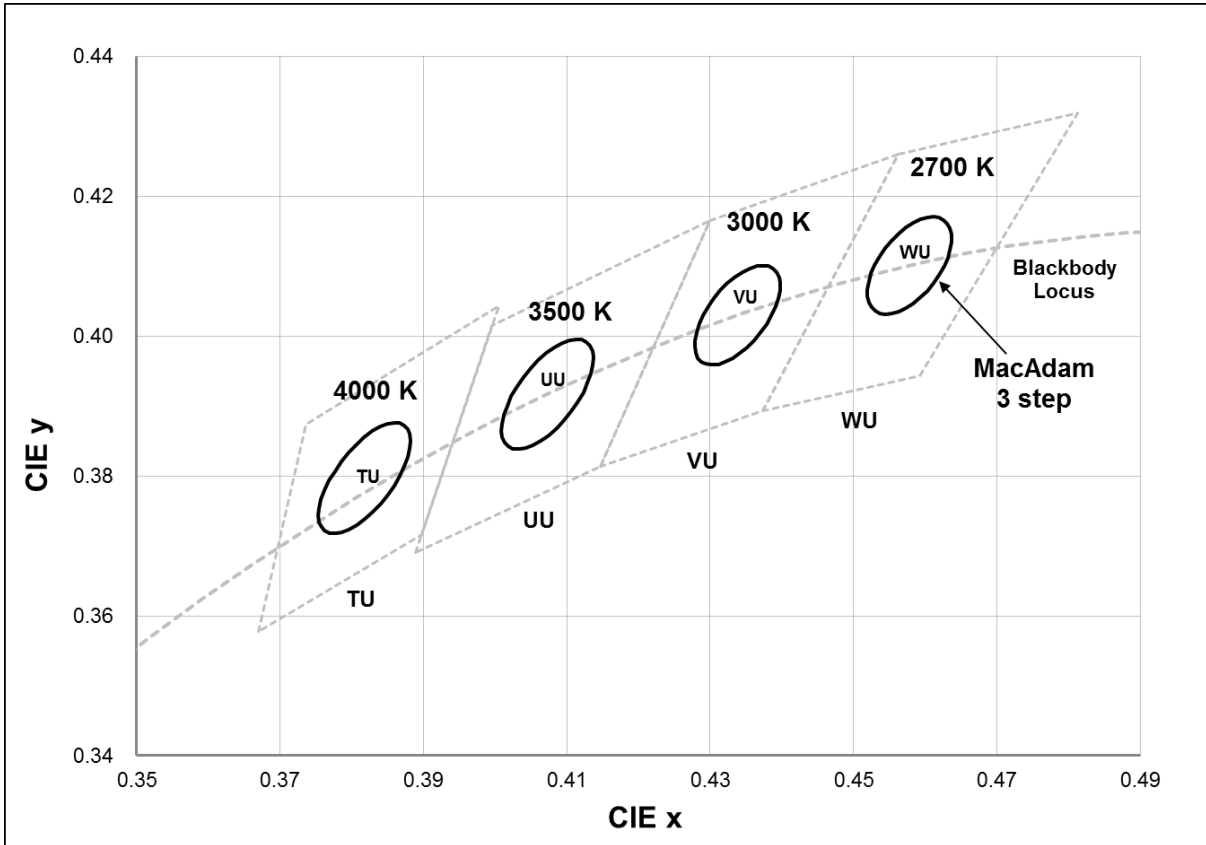
**c) Voltage Bins** ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

Nominal CCT /K	CRI Min	Product Code	Voltage Rank	Voltage Bin	Voltage Range /V
			3F	39	5.6 ~ 5.9
				9F	5.9 ~ 6.2

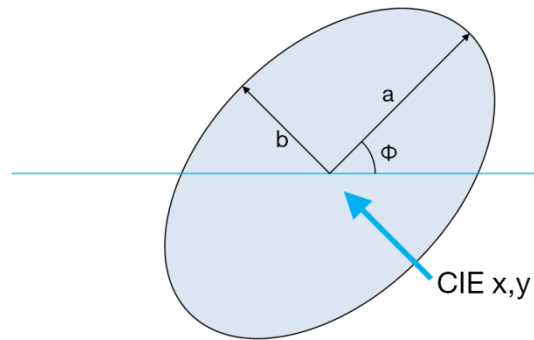
d) Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ ) : "L" (Full bin for MacAdam 5-step)



d) Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ ) : "U" (Single for MacAdam 3-step)



d) Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )



	CCT (K)	Center point		Major-axis	Minor-axis	Rotation
		CIE x	CIE y	a	b	$\phi$
3 step (U code)	2700	0.4578	0.4101	0.0081	0.0042	53.70
	3000	0.4338	0.4030	0.0083	0.0041	53.22
	3500	0.4073	0.3917	0.0093	0.0041	54.00
	4000	0.3818	0.3797	0.0094	0.0040	53.72
	5000	0.3447	0.3553	0.0082	0.0035	59.62
	5700	0.3287	0.3417	0.0075	0.0032	59.10
	6500	0.3123	0.3282	0.0067	0.0029	58.57
5 step (L code)	2700	0.4578	0.4101	0.0135	0.0070	53.70
	3000	0.4338	0.4030	0.0138	0.0068	53.22
	3500	0.4073	0.3917	0.0155	0.0068	54.00
	4000	0.3818	0.3797	0.0157	0.0067	53.72
	5000	0.3447	0.3553	0.0137	0.0058	59.62
	5700	0.3287	0.3417	0.0125	0.0053	59.10
	6500	0.3123	0.3282	0.0112	0.0048	58.57

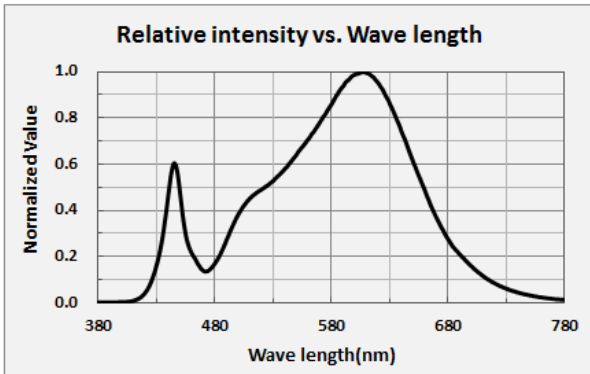
**Note:** Samsung maintains measurement tolerance of:  $C_x, C_y = \pm 0.005$



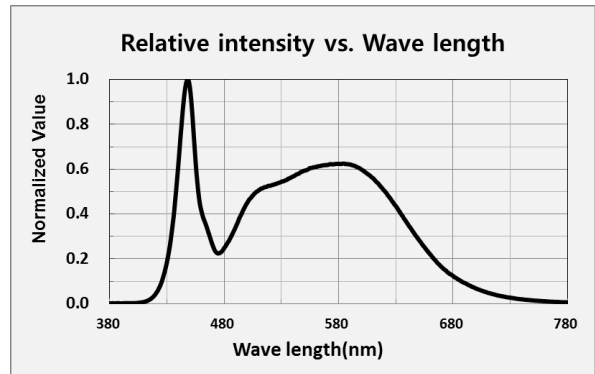
### 3. Typical Characteristics Graphs

#### a) Spectrum Distribution ( $I_F = 150 \text{ mA}$ , $T_s = 25 \text{ }^\circ\text{C}$ )

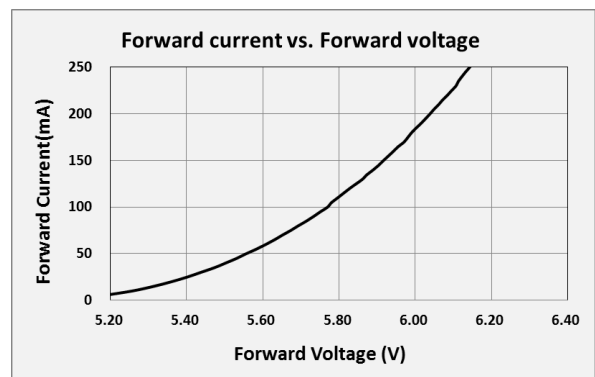
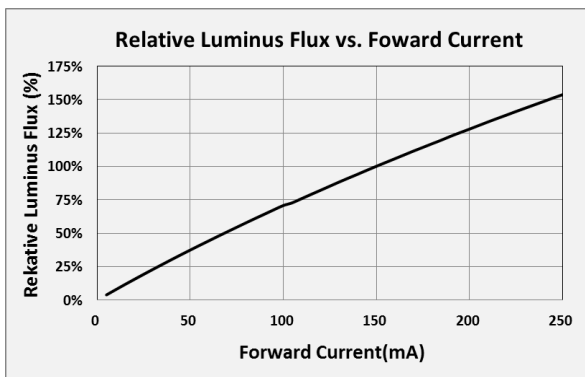
CCT : 2700K



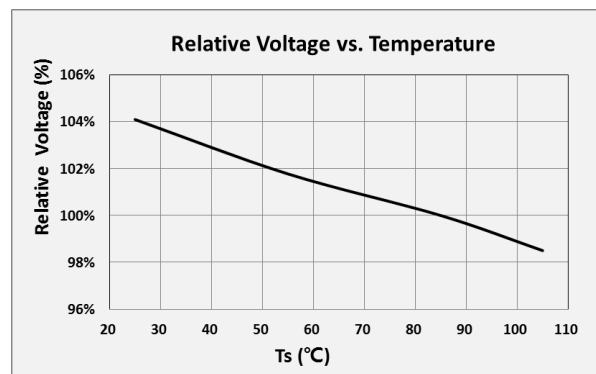
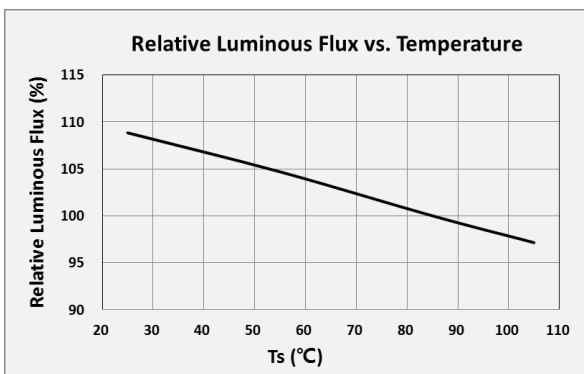
CCT : 5000K



#### b) Forward Current Characteristics ( $T_s = 25 \text{ }^\circ\text{C}$ )



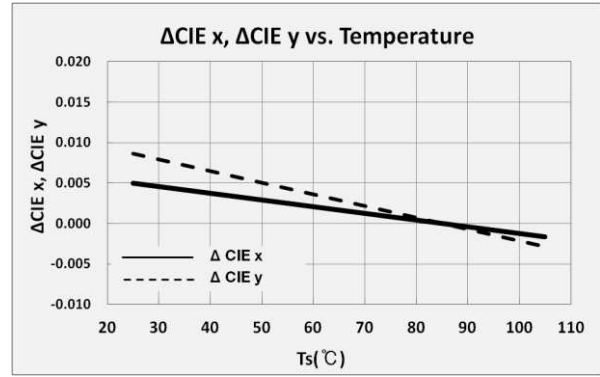
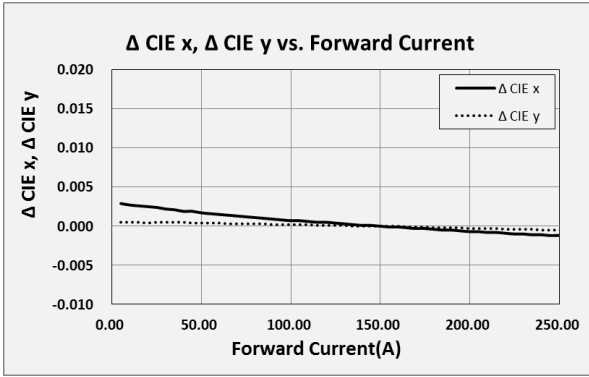
#### c) Temperature Characteristics ( $I_F = 150 \text{ mA}$ )



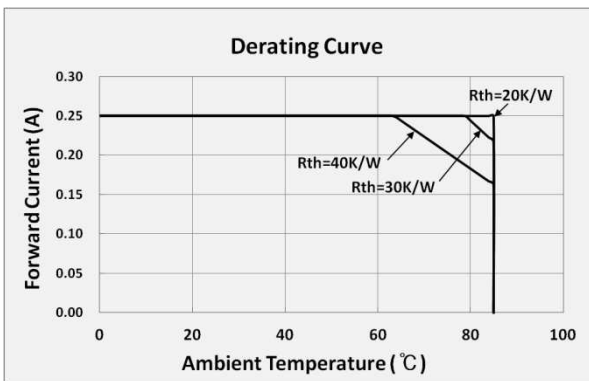
d) Color Shift Characteristics

$T_s = 25\text{ }^\circ\text{C}$

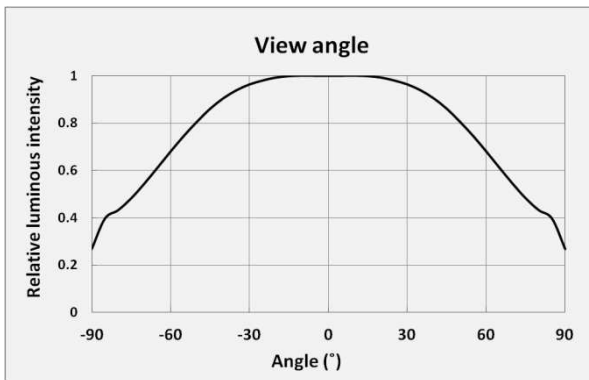
$I_F = 150\text{ mA}$



e) Derating Curve



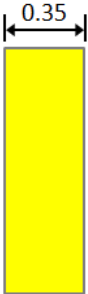
f) Beam Angle Characteristics ( $I_F = 150\text{ mA}$ )



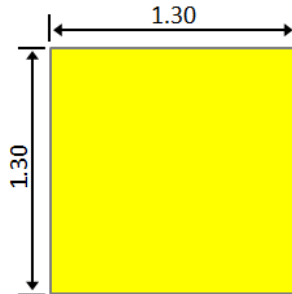
## 4. Outline Drawing & Dimension

1. Tolerance is  $\pm 0.10$  mm
2. Do not place LEDs with pressure

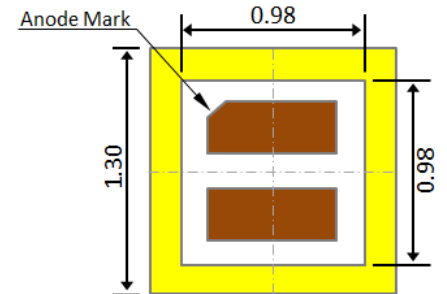
<Side View>



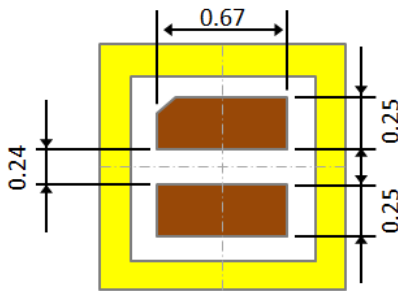
<Top View>



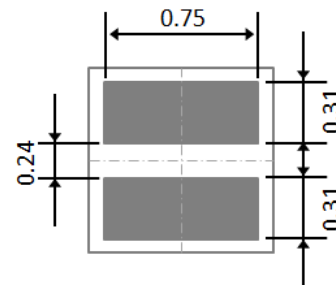
<Bottom View>



<Recommended Land Pattern>



<Chip Pad>



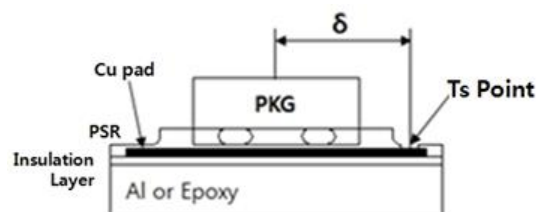
<PCB Land>

### $T_s$ Point & Measurement Method:

Measure nearest point from the center of LED chip ( $\delta$ ) as shown below.

Distance between chip center and  $T_s$  point ( $\delta$ ) = 3.5 mm

$$T_j = T_s + \text{Power} \times \text{Thermal resistance at } T_s (R_{j-s})$$



**Precautions:**

- 1) This LED chip PKG does not contain built-in ESD protection device.
- 2) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 3) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED`s characteristics should be carefully checked before and after such repair.
- 4) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

### a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample Size
Room Temperature Life Test	25 °C, DC 250 mA	1000 h	22
High Temperature Life Test	85 °C, DC 250 mA	1000 h	22
High Temperature Humidity Life Test	85 °C, 85 % RH, DC 250 mA	1000 h	22
Low Temperature Life Test	-40 °C, DC 250 mA	1000 h	22
Powered Temperature Cycle Test	-45 °C / 20 min ↔ 85 °C / 20 min, sweep 100 min cycle on/off: each 5 min, DC 250 mA	100 cycles	22
Thermal Shock	-45 °C / 15 min ↔ 125 °C / 15 min → Hot plate 180 °C	800 cycles	100
High Temperature Storage	120 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	 <p> <math>R_1</math>: 10 M<math>\Omega</math>  <math>R_2</math>: 1.5 k<math>\Omega</math>  <math>C</math>: 100 pF  <math>V</math>: <math>\pm 5</math> kV         </p>	5 times	5
Vibration Test	20~2000~20 Hz, 200 m/s <sup>2</sup> , sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles	11
Mechanical Shock Test	1500 g, 0.5 ms	5 cycles	11

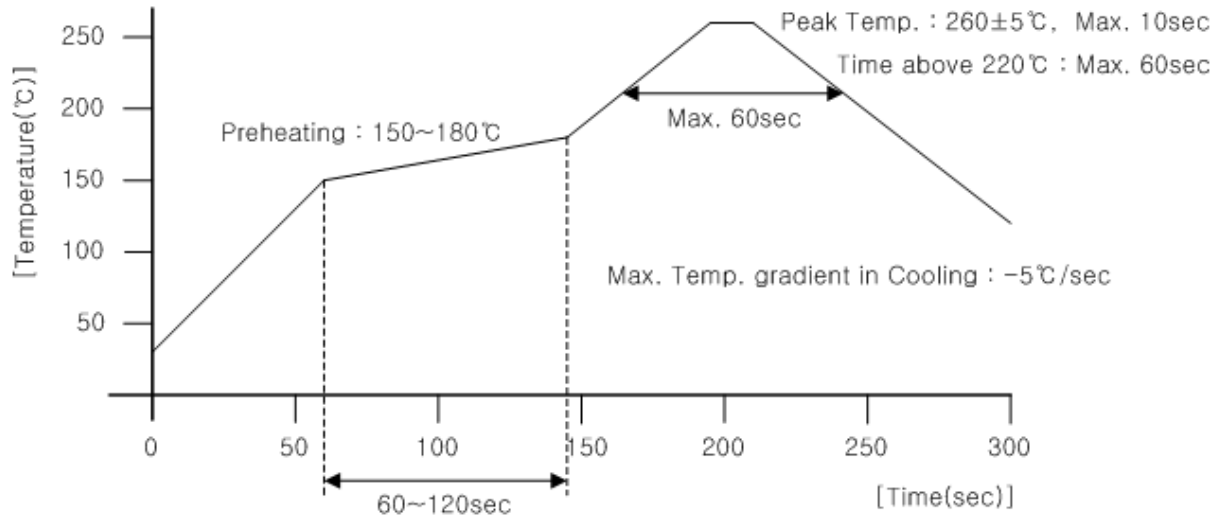
### b) Criteria for Judging the Damage

Item	Symbol	Test Condition ( $T_s = 25$ °C)	Limit	
			Min	Max
Forward Voltage	$V_F$	$I_F = 250$ mA	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	$\Phi_v$	$I_F = 250$ mA	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

### a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



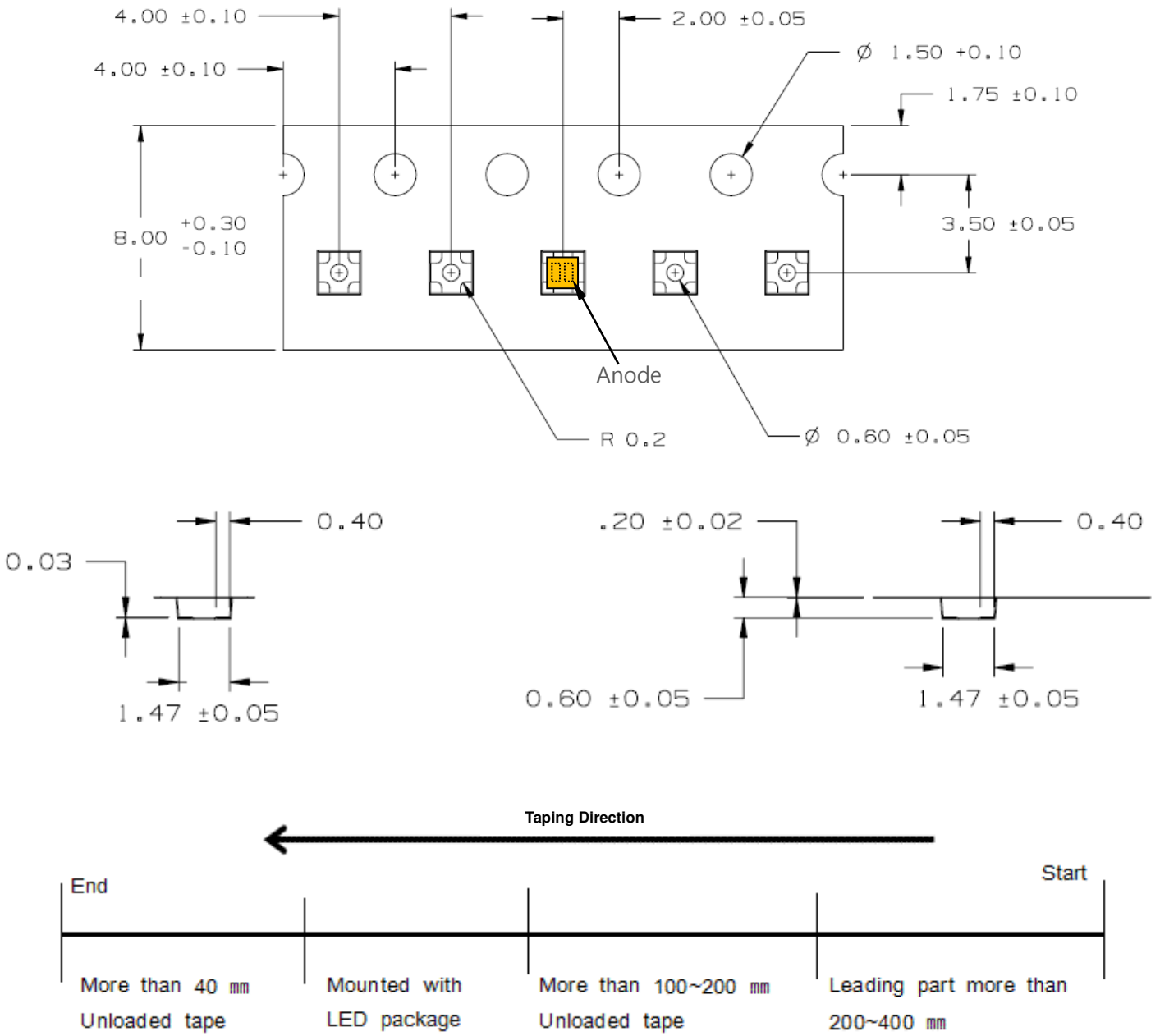
### b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

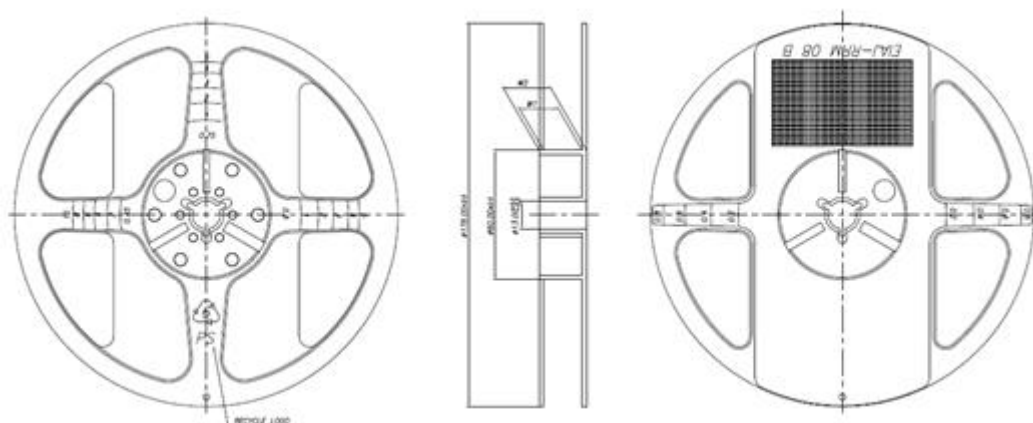
## 7. Tape & Reel

### a) Taping Dimension

(unit: mm)



## b) Reel Dimension



Width	W1	W2
8mm	9 ±0.3	11.9 ±1.0

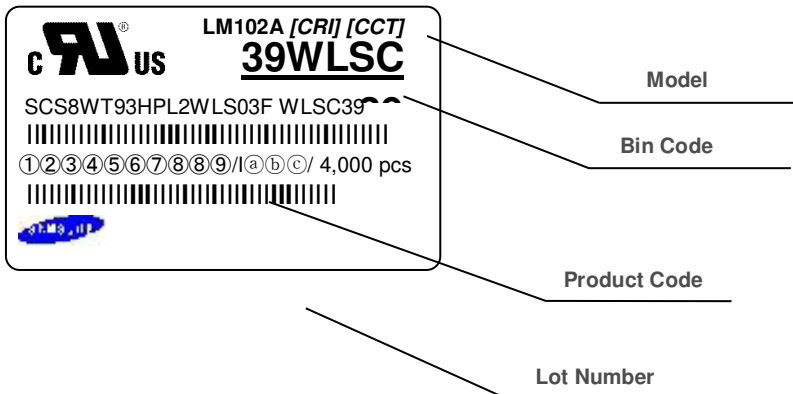
### Notes:

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is  $\pm 0.2$  mm
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag



## 8. Label Structure

### a) Label Structure



Note: Denoted product code and bin code above is only an example

Rank Code:

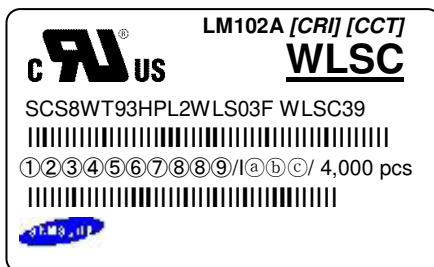
①②: Chromaticity bin (refer to page 10-11)

③④: Luminous Flux bin (refer to page 7)

⑤⑥: Forward Voltage bin (refer to page 12)

### b) Lot Number

The lot number is composed of the following characters:



①②③④⑤⑥⑦⑧⑨ / | a b c / 4,000 pcs

①② : Production site (G3: Shenzhen China, G4: Guangzhou China, GB: Nanchang China)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

④ : Year (Y: 2014, Z: 2015, A: 2016 ...)

⑤ : Month (1~9, A, B, C)

⑥ : Day (1~9, A, B~V)

⑦⑧⑨ : Product serial number (001 ~ 999)

ⒶⒷⒸ : Reel number (001 ~ 999)